

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT4302696

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
RYO MIYAKE	05/07/2015
KIYOSHI OOTA	05/18/2015
SHOGO YASHIRO	05/19/2015
JUN KATSUMATA	05/04/2015
KOK KEONG LIM	05/04/2015
DAIGAKU KUMANO	05/19/2015
TOMOHIRO ITO	05/11/2015
TAKESHI INOUE	05/12/2015
DAISUKE MATSUO	05/14/2015
HISAHIRO TANAKA	05/11/2015
HIROMI INUKAI	05/19/2015
SHIGEYA KUWAO	05/18/2015
RECEIVING PARTY DATA	
Name:	SONY CORPORATION
Street Address:	1-7-1 KONAN
City:	MINATO-KU, TOKYO
State/Country:	JAPAN
Postal Code:	108-0075
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	29519237
CORRESPONDENCE DATA	
Fax Number:	(414)277-0656
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Email:	nncondie@michaelbest.com, dcipdocket@michaelbest.com
Correspondent Name:	MICHAEL BEST & FRIEDRICH LLP
Address Line 1:	100 EAST WISCONSIN AVENUE
Address Line 2:	SUITE 3300
Address Line 4:	MILWAUKEE, WISCONSIN 53202

PATENT

ATTORNEY DOCKET NUMBER:	880201-2955-US01
NAME OF SUBMITTER:	BRIAN K. DUTTON/NNC
SIGNATURE:	/Brian K. Dutton/
DATE SIGNED:	03/03/2017

Total Attachments: 12

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DECLARATION AND ASSIGNMENT

EARPHONE

As a below named inventor, I hereby declare that:

This declaration is directed to:

- ☐ the attached application, or
☒ United States application or PCT international application number
29/519,237, filed on March 3, 2015.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

I have reviewed and understand the contents of the above-identified application, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations § 1.56.

WHEREAS, the below named inventor(s) have invented certain new and useful improvements described in the above-identified application,

AND WHEREAS, **Sony Corporation, 1-7-1 Konan, Minato-ku, Tokyo 108-0075, Japan**, a corporation of Japan (hereinafter referenced as ASSIGNEE), is desirous of acquiring all interest in, to and under the invention, the above-identified application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, have assigned, sold and transferred, and do hereby assign, sell and transfer unto the ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the invention and the above-identified application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for the invention, and in and to any all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America

adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

This assignment executed on the date(s) indicated below.

Ryo MIYAKE
Legal Name of Inventor

Ryo Miyake
Signature of Inventor

Date May 7, 2015

☒ Additional inventors are named on the supplemental sheet(s) attached hereto.

SUPPLEMENTAL SHEET(S) FOR DECLARATION AND ASSIGNMENT

Kiyoshi OOTA

Legal Name of Joint Inventor (if applicable)



Signature of Joint Inventor

Date May 18, 2015

Shogo YASHIRO

Legal Name of Joint Inventor (if applicable)



Signature of Joint Inventor

Date May 19, 2015

Jun KATSUMATA

Legal Name of Joint Inventor (if applicable)

Signature of Joint Inventor

Date _____

Kok Kenng LIM

Legal Name of Joint Inventor (if applicable)

Signature of Joint Inventor

Date _____

Daigaku KUMANO

Legal Name of Joint Inventor (if applicable)



Signature of Joint Inventor

Date May 19, 2015

Tomohiro ITO

Legal Name of Joint Inventor (if applicable)

Signature of Joint Inventor

Date _____

Client Reference No.: SD353774US01

Attorney Docket No: SDE-2955/CIP

Takeshi INOUE

Legal Name of Joint Inventor (if applicable)

Signature of Joint Inventor

Date _____

Daisuke MATSUO

Legal Name of Joint Inventor (if applicable)

Signature of Joint Inventor

Date _____

Hisahiro TANAKA

Legal Name of Joint Inventor (if applicable)

Signature of Joint Inventor

Date _____

Hiromi INUKAI

Legal Name of Joint Inventor (if applicable)

Hiromi Inukai

Signature of Joint Inventor

Date May 19, 2015

Shigeo KUWAO

Legal Name of Joint Inventor (if applicable)

Shigeo Kuwao

Signature of Joint Inventor

Date May 18, 2015

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adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

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Ryo MIYAKE
Legal Name of Inventor

Signature of Inventor

Date _____

☒ Additional inventors are named on the supplemental sheet(s) attached hereto.

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Kiyoshi OOTA
Legal Name of Joint Inventor (if applicable)

Signature of Joint Inventor

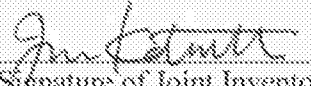
Date _____

Shogo YASHIRO
Legal Name of Joint Inventor (if applicable)

Signature of Joint Inventor

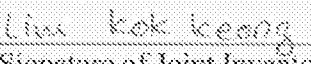
Date _____

Jun KATSUMATA
Legal Name of Joint Inventor (if applicable)


Signature of Joint Inventor

Date May 4, 2015

Kok Keeng LIM
Legal Name of Joint Inventor (if applicable)


Signature of Joint Inventor

Date May 4, 2015

Daigaku KUMANO
Legal Name of Joint Inventor (if applicable)

Signature of Joint Inventor

Date _____

Tomohiro ITO
Legal Name of Joint Inventor (if applicable)

Signature of Joint Inventor

Date _____

Client Reference No.: SD353774US01

Attorney Docket No: SDE-2955/CIP

Takeshi INQUE

Legal Name of Joint Inventor (if applicable)

Signature of Joint Inventor

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Daisuke MATSUO

Legal Name of Joint Inventor (if applicable)

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Hisahiro TANAKA

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Signature of Inventor

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Signature of Joint Inventor

Date _____

Tomohiro ITO

Legal Name of Joint Inventor (if applicable)

Tomohiro Ito
Signature of Joint Inventor

Date May 11 2015

Client Reference No.: SD353774US01
Attorney Docket No: SDE-2955/CIP

Takeshi INOUE
Legal Name of Joint Inventor (if applicable)

Takeshi Inoue
Signature of Joint Inventor

Date May. 12, 2015

Daisuke MATSUO
Legal Name of Joint Inventor (if applicable)

Daisuke MATSUO
Signature of Joint Inventor

Date May. 14, 2015

Hisahiro TANAKA
Legal Name of Joint Inventor (if applicable)

Hisahiro Tanaka
Signature of Joint Inventor

Date May. 11, 2015

Hiromi INUKAI
Legal Name of Joint Inventor (if applicable)

Signature of Joint Inventor

Date _____

Shigeo KUWAO
Legal Name of Joint Inventor (if applicable)

Signature of Joint Inventor

Date _____